

L Number	Hits	Search Text	DB	Time stamp
1	240	(427/335).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/22 13:17
2	475	(427/336).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/22 13:12
3	75	((427/335).CCLS.) or ((427/336).CCLS.) and (resist or photoresist or novolac)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/22 13:18
4	487	(427/340).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/22 13:18
5	99	((427/335).CCLS.) or ((427/336).CCLS.) or ((427/340).CCLS.) and (resist or photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/22 13:18
6	3	((427/335).CCLS.) or ((427/336).CCLS.) or ((427/340).CCLS.) and (solvent same PGMEA)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/22 13:19
-	2	"6355198"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/22 11:48
-	1	2002-461607.NRAN.	DERWENT	2003/09/24 15:37
-	0	6355198.URPN.	USPAT	2003/09/24 15:37
-	25	(polymer and mold and capillary).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 13:40
-	252	(polymer and mold and pattern).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 15:42
-	46	(polymer and mold and (heat adj treat\$4)).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 15:43
-	41	((polymer or resin) and mold and capillary).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 15:43
-	0	("(capillaryandmicromolding).ti.").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 15:44
-	2	(capillary and micromolding).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 15:45

-	3	(capillary and micromolding).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:50
-	9	(micromolding).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:45
-	22	(micromolding).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:45
-	20638	((polymer or resin) and molding).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:47
-	293	whitesides.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:48
-	45	whitesides.in. and printing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:52
-	22	(microcontact adj printing).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/17 15:27
-	151	whitesides.in. and (polymer or resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:50
-	10	(capillary and molding).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:50
-	10	whitesides.in. and (PGMEA or novolac)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:49
-	102	(216/44).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:58
-	738	(216/2).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/24 15:56
-	34	("3873359" "3873360" "3900614" "4098922" "4100037" "4192764" "4258001" "4322457" "4472458" "4508755" "4555414" "4637904" "4690715" "4710401" "4728591" "4802951" "4869778" "4959252" "5073495" "5079600" "5087510" "5141785" "5170461" "5227474" "5259926" "5345869" "5385116" "5393401" "5439829" "5471455" "5484324" "5512131" "5620850" "5976826").PN.	USPAT	2003/09/24 15:57

-	242	(216/54).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 15:58
-	479	(216/33).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 16:01
-	1052	(216/41).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 16:02
-	1938	(264/259).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 16:03
-	1431	(264/299).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 16:04
-	397	(264/330).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 16:04
-	532	(264/331.11).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/24 16:04
-	829	(\$5contact adj print\$3).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 15:28
-	52	(\$5contact adj print\$3).ti. and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 15:28
-	6	(\$5contact adj print\$3).ti. and capillary	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 15:29
-	4	(\$5contact adj print\$3).ti. and capillary and polymer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/17 15:29
-	10	whitesides.in. and (novolac)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 11:49
-	1436	(polymer and capillary).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 11:51
-	2	(polymer and capillary).ab. and PGMEA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 11:51

-	1	whitesides.in. and (PGMEA)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 11:52
-	145	photoresist with PGMEA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 18:55
-	645	photoresist with novolac	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 16:21
-	0	micromoulding near3 capillaries	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:24
-	0	micromoulding near3 capillaries	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:25
-	46	micromolding near3 capillaries	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:39
-	6	(micromolding near3 capillaries) and (novolac)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:33
-	18	(micromolding near3 capillaries) and (photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:34
-	7	(micromolding near3 capillaries) and (inorganic with mold)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:46
-	25	(polymer and mold and capillar\$3).clm.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:40
-	0	(pourous adj silicon) with mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:54
-	218	(silicon adj dioxide) with mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:57
-	399	("sio.sub.2") with mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:57
-	10	(silicon adj dioxide) with (mold and (porous or porosity))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/10/21 13:55

-	19	("sio.sub.2") with (mold and (porous or porosity))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 13:55
-	7	(silicon adj dioxide) adj mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 13:57
-	18	("sio.sub.2") adj mold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 13:57
-	2	("6329211").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 14:32
-	2	photoresist with novolac with PGMEA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 16:22
-	5	photoresist same novolac same PGMEA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 17:09
-	3090	damascene and photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 17:10
-	679	damascene and photoresist and copper and wiring and pattern	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 17:14
-	9397	copper adj clad\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 17:13
-	1101	(216/13).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 17:15
-	335	((216/13).CCLS.) and (resist or photoresist) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 17:17
-	244	((216/13).CCLS.) and (resist or photoresist) and pattern with (wiring or conduct\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 17:18
-	345	photoresist with (novolac adj resin)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:15
-	15	(photoresist same (novolac adj resin)) and PGMEA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:27

-	10	photoresist and (PGMEA with evaporat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:23
-	35	photoresist and (PGMEA same evaporat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:36
-	36	(photoresist same novolac) and PGMEA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:27
-	38	(photoresist same novolac\$1) and PGMEA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:34
-	107	photoresist and (PGMEA same heat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:28
-	23	photoresist and (PGMEA with heat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:29
-	27	(photoresist same fluidiz\$3) and (evaporat\$3 or vapor\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:35
-	15	PGMEA same evaporat\$3 same resin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:42
-	39	(PGMEA or polymer or resin or solvent) and (sealed adj vessel) and photoresist	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:46
-	1720	(PGMEA or polymer or resin or solvent) and (sealed adj vessel) and (diffus\$5 or permeat\$5 or evaporat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:46
-	22	((PGMEA or polymer or resin or solvent) and (sealed adj vessel) and (diffus\$5 or permeat\$5 or evaporat\$3)).ab.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:48
-	484	(solvent and (polymer or photoresist)) and (sealed adj vessel) and (diffus\$5 or permeat\$5 or evaporat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:52
-	258	(solvent and (polymer or photoresist)) and (sealed adj vessel) and (diffus\$5 or permeat\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:50
-	8	(solvent and (polymer and photoresist)) and (sealed adj vessel) and (diffus\$5 or permeat\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:51

-	116	(solvent same vapor) same diffusion same (resin or polymer or photoresist)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:53
-	679	photoresist and PGMEA	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 18:55
-	166	photoresist and PGMEA and (diffusion)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 19:13
-	9	(fluidizing and polymer).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 19:14
-	0	(fluidizing and photoresist).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 19:14
-	534	(solvent and photoresist).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 19:23
-	4	(solvent and photoresist and vapor).ti.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/21 19:25
-	12	(solvent and photoresist and vapor).ab.	USPAT; US-PGPUB	2003/10/21 19:27
-	20	(solvent and resist and vapor).ab.	USPAT; US-PGPUB	2003/10/22 11:14
-	31	(solvent and (resist or photoresist) and (chamber or vessel)).ab.	USPAT; US-PGPUB	2003/10/22 10:55
-	19	(solvent and resist and (chamber or vessel)).ab.	USPAT; US-PGPUB	2003/10/22 10:57
-	43	(solvent and resist and (absorb\$3 or diffus\$3 or evaporat\$3 or permeat\$3)).ab.	USPAT; US-PGPUB	2003/10/22 10:58
-	83	(solvent and resist).ab. and PGMEA	USPAT; US-PGPUB	2003/10/22 11:00
-	532	(solvent and resist).ab.	USPAT; US-PGPUB	2003/10/22 11:10
-	23	((("3737499") or ("3597257") or ("3539381") or ("3339526") or ("2294479") or ("2138578"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/22 11:11
-	7	("0243200" "2138578" "2294479" "3339526" "3539381" "3597257" "3737499").PN.	USPAT	2003/10/22 11:13
-	16	4022932.URPN.	USPAT	2003/10/22 11:13
-	23	(solvent and resist and (chamber or vessel or container)).ab.	USPAT; US-PGPUB	2003/10/22 11:15
-	37	(solvent and (photoresist or resist) and (chamber or vessel or container)).ab.	USPAT; US-PGPUB	2003/10/22 11:18
-	4	((("5374693") or ("5614349"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/22 11:18
-	10	((("4315985") or ("6143412") or ("6004444") or ("5965237"))).PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/22 11:48